



Docket No.: 50090-470

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

In re Application of

Masatoshi YASUNAGA

Serial No.: 10/057,923 ✓

Filed: January 29, 2002

For: SEMICONDUCTOR DEVICE

Group Art Unit: 2811

Examiner: D. Nguyen

6/A
Step 1
7-24-02

AMENDMENT

Commissioner for Patents
Washington, DC 20231

Sir:

The following Amendment and Remarks are submitted in response to the Office
Action dated April 10, 2002.

IN THE CLAIMS:

Please amend claims 1, 7, 9 and 12 as follows.

1. (Amended) A semiconductor device comprising:
 - a substrate;
 - a semiconductor chip mounted on the substrate;
 - external electrodes provided on the back of the substrate, for connecting electrodes of the semiconductor chip to the outside;
 - a sealing member encapsulating the semiconductor chip on the substrate; and
 - a heat sink plate fixed by the sealing member, wherein

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